

In the Claims:

1. (Original) An integrated circuit comprising:
 - a substrate;
 - a first insulating layer on the substrate that includes therein a first hole passing therethrough that includes a floor adjacent the substrate and a sidewall;
 - a first conductive contact that extends conformally on the sidewall and floor to define a groove in the first hole;
 - a second insulating layer on the first insulating layer remote from the substrate that includes therein a second hole passing therethrough that exposes the groove; and
 - a second conductive contact in the second hole and in the groove.
2. (Original) An integrated circuit according to Claim 1 wherein the floor is directly on the substrate.
3. (Original) An integrated circuit according to Claim 1 wherein the second conductive contact fills the second hole and the groove.
4. (Original) An integrated circuit according to Claim 1 wherein the first conductive contact comprises a first barrier layer on the sidewall and floor and a first conductive layer on the first barrier layer remote from the sidewall and floor and wherein the second conductive contact comprises a second barrier layer on the first conductive layer and a second conductive layer on the second barrier layer remote from the first conductive layer.
5. (Original) An integrated circuit according to Claim 4 wherein the first and second barrier layers comprise titanium and/or titanium nitride and wherein the first and second conductive layers comprise tungsten.
6. (Original) An integrated circuit according to Claim 1 wherein the first conductive contact also extends onto the first insulating layer outside the first hole.
7. (Original) An integrated circuit according to Claim 1 wherein the second conductive contact also extends onto the second insulating layer outside the second hole.

8. (Original) An integrated circuit according to Claim 1:
wherein the first insulating layer includes a third hole and a fourth hole passing therethrough; and
wherein the second insulating layer includes a fifth hole passing therethrough that exposes the fourth hole;
the integrated circuit further comprising:
a third conductive contact in the third hole; and
a fourth conductive contact in the fourth and fifth holes.
9. (Original) An integrated circuit according to Claim 8 further comprising:
a third insulating layer on the second insulating layer remote from the first insulating layer that includes therein a sixth hole that exposes the second hole;
the second conductive contact further extending into the sixth hole.
10. (Original) An integrated circuit according to Claim 8 further comprising:
a capacitor on the second insulating layer that is electrically connected to the fourth conductive contact.
11. (Original) An integrated circuit according to Claim 9 wherein the second conductive contact also extends onto the third insulating layer outside the sixth hole.
12. (Original) An integrated circuit according to Claim 8 wherein the first hole is at least twice as wide as the third hole.
- 13.-26. (Canceled)
27. (Original) An integrated circuit according to Claim 4 wherein the first insulating layer includes a third contact hole and a fourth contact hole passing therethrough; and
wherein the second insulating layer includes a fifth hole passing therethrough that exposes the fourth hole;

the integrated circuit further comprising:
a third conductive contact in the third contact hole; and
a fourth conductive contact in the fourth and fifth holes.

28. (Original) An integrated circuit according to Claim 7 wherein the third conductive contact comprises a third barrier layer that extends conformally inside the third contact hole and a third conductive layer on the third barrier layer.

29. (Original) An integrated circuit according to Claim 27 wherein the third conductive contact also extends onto the first insulating layer outside the third contact hole.

30. (Original) An integrated circuit according to Claim 27 wherein the first hole is at least twice as wide as the first conductive contact.